**LH250 – CERAMIC HERMETIC SMT PACKAGE**

**LH250 Package Outline Drawing**

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**NOTES:**

1. **PACKAGE MATERIAL:** CERAMIC & KOVAR.
2. **LEAD AND GROUND PADDLE PLATE:** GOLD 40 - 80 MICROINCHES.
3. **DIMENSIONS ARE IN INCHES [MILLIMETERS].**
4. **LEAD SPACING TOLERANCE IN NON-CUMULATIVE.**
5. **PAD BUR LENGTH 0.15mm MAX. PAD BUR HEIGHT 0.25mm MAX.**
6. **ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.**
Suggested LH250 PCB Land Pattern

NOTES:
1. DIMENSIONS ARE IN INCHES [MILLIMETERS].
2. PAD WIDTH SHOWN IS FOR SOLDERING ONLY. BEYOND SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM CHARACTERISTIC IMPEDANCE.